IPC ASSOCIATION ELECTRONIC	© Copyrig	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both lev	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		Site for Information ow.ipc.org/IPC-175x	rdard Form Type * Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg	Informat	ion		
Supplie	r Information	•							·						
ompany	name*		Company un	Company unique ID			Unique ID Authority					Response Date*			
nsemi												2024-05-04			
Contact N	Name		Title - Contac	Title - Contact			Phone - Contact*					Email - Contact*			
Product-l	Env-Stewards		Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards		Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Requester Item Number Mfr Item		m Number Mfr Item Name		I	Effective Date	Version	N	Manufacturing Site		W	eight*	UOM	Unit Type
		NVMFD5873NLT1G		NFET SO8FL 60V 58A 13MOHM		2	2024-05-04					13	6.09	mg	Each
Ianufa	acturing Proccess In	nformation													
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STI		-STD-020 MSL R	lating	Peak Proce	ess Body To	ss Body Temperature Max Time at Peak		ne at Peak	Temperatur	e Numb	per of Reflow Cyc	les
Matte Tin (Sn) - annealed			CU Alloy	CU Alloy 1			260 C 30				seconds 3				
omments	S														
vel 1 - m	naximum time at peak t	temperature during	soldering is 10-3	0 seconds											
or more	information regarding	material compositi	on please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.76	mg	Supplier	Silicon (Si)	7440-21-3		6.76	mg
Die Attach Solder	11.9	mg	Supplier	Silver (Ag)	7440-22-4		0.2975	mg
			A	Lead (Pb)	7439-92-1	7a	11.0075	mg
			Supplier	Tin (Sn)	7440-31-5		0.595	mg
Lead Frame	83.05	mg	Supplier	Iron (Fe)	7439-89-6		0.5814	mg
			Supplier	Copper (Cu)	7440-50-8		82.4687	mg
Mold Compound-Black	33.33	mg		Epoxy Phenol Resin	proprietary data		3.4997	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.8304	mg
Plating	0.95	mg	Supplier	Tin (Sn)	7440-31-5		0.95	mg
Wire Bond - Cu	0.1	mg	Supplier	Copper (Cu)	7440-50-8		0.1	mg